

# HA17324/A Series

## Quad Operational Amplifier

# HITACHI

ADE-204-031 (Z)

1st Edition

Apr. 2000

### Description

HA17324 series and HA17324A series are quad operational amplifier that provide high gain and internal phase compensation, with single power supply. They can be widely used to control equipments.

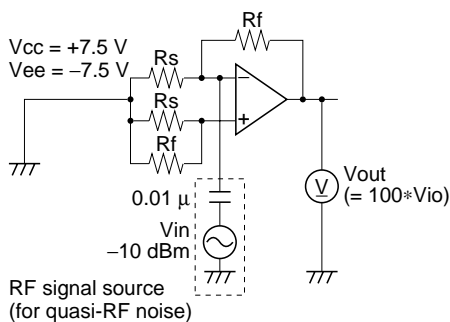
### Features

- Wide range of supply voltage, and single power supply used
- Internal phase compensation
- Wide range of common mode voltage, and possible to operate with an input about 0V

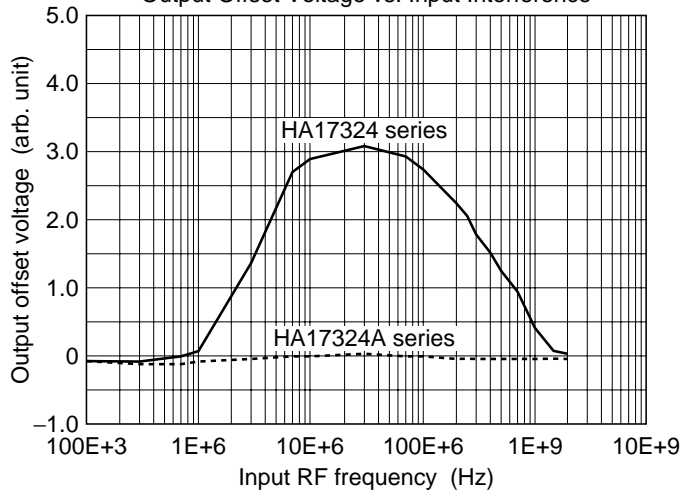
### Features only for “A” series

- Low electro-magnetic interference level

Measurement Condition



Output Offset Voltage vs. Input Interference



Notice: The example of an applied circuit or combination with other equipment shown herein indicates characteristics and performance of semiconductor -applied products.

The company shall assume no responsibility for any problem involving a patent caused when applying the descriptions in the example.

# HA17324/A Series

## Ordering Information

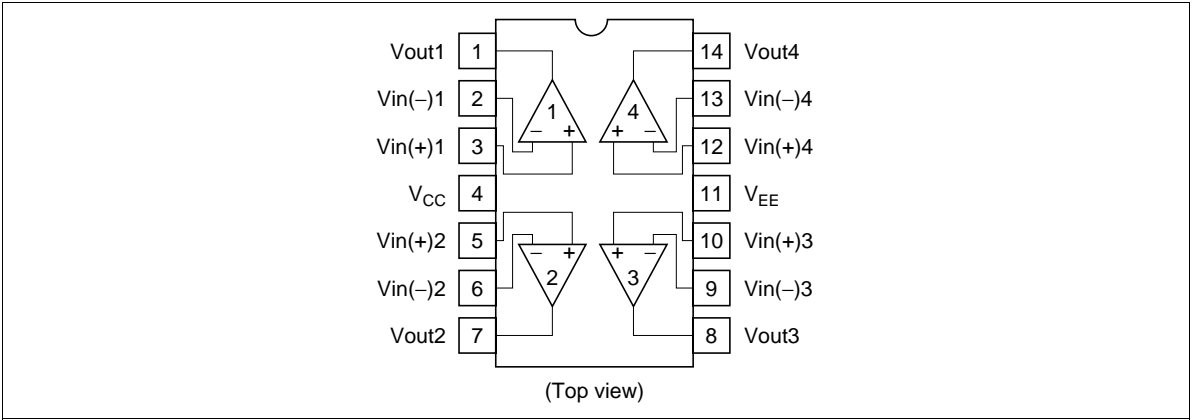
### HA17324 Series

Type No.	Application	Package
HA17324P	Industrial use	DP-14
HA17324FP		FP-14DA
HA17324	Commercial use	DP-14
HA17324F		FP-14DA

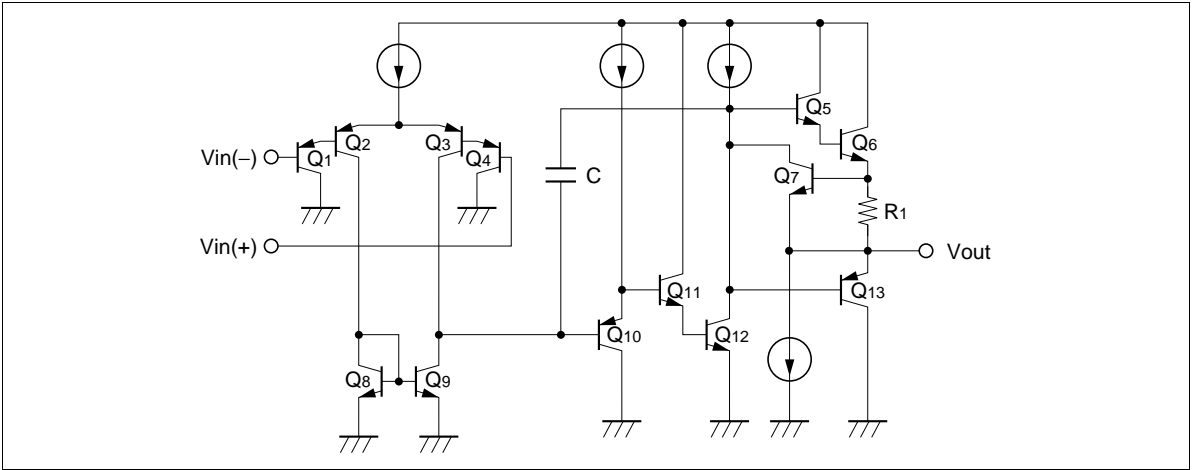
### HA17324A Series

Type No.	Application	Package
HA17324AP	Industrial use	DP-14
HA17324ARP		FP-14DN
HA17324AFP		FP-14DA

Pin Arrangement



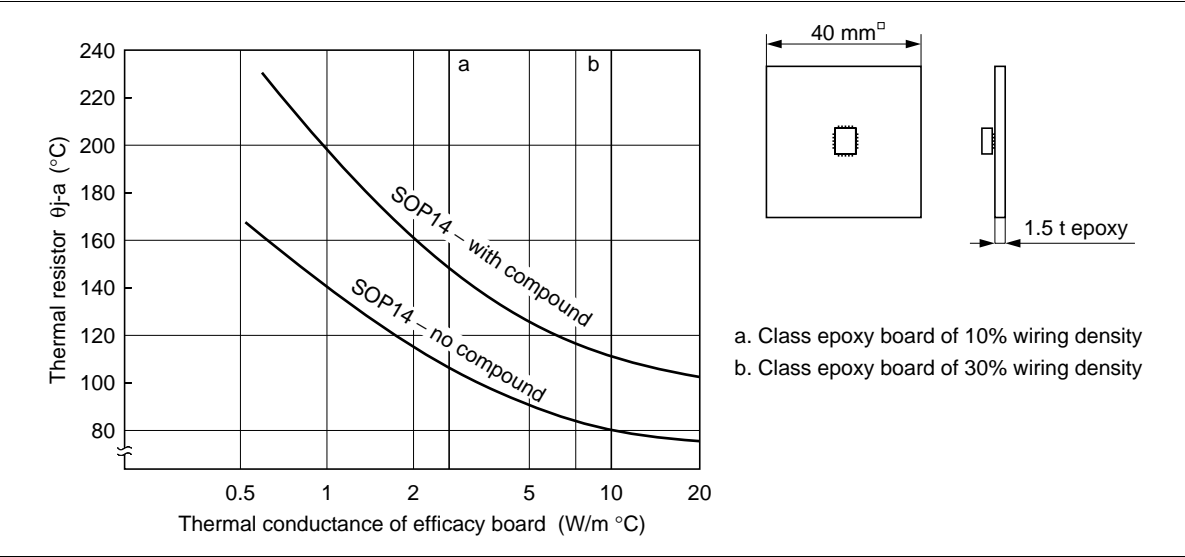
Circuit Schematic (1/4)



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings		Unit
		HA17324/P/AP	HA17324F/FP/ARP/AFP	
Supply voltage	V <sub>CC</sub>	32	32	V
Sink current	I <sub>sink</sub>	50	50	mA
Power dissipation	P <sub>T</sub>	625 * <sup>1</sup>	625 * <sup>2</sup>	mW
Common mode input voltage	V <sub>CM</sub>	−0.3 to V <sub>CC</sub>	−0.3 to V <sub>CC</sub>	V
Differential input voltage	V <sub>in</sub> (diff)	±V <sub>CC</sub>	±V <sub>CC</sub>	V
Operating temperature	Topr	−20 to +75	−20 to +75	°C
Storage temperature	Tstg	−55 to +125	−55 to +125	°C

Notes: 1. This is the allowable values up to Ta = 50°C. Derate by 8.3 mW/°C.  
2. Tjmax = θj-a · P<sub>C</sub>max + Ta (θj-a; Thermal resistor between junction and ambient at set board use).  
The wiring density and the material of the set board must be chosen for thermal conductance of efficacy board.  
And P<sub>C</sub>max cannot be over the value of P<sub>T</sub>.

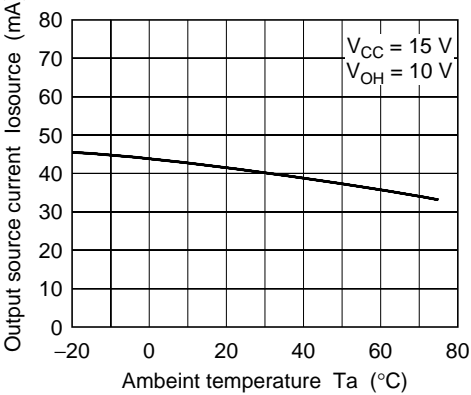


Electrical Characteristics ( $V_{CC} = +15\text{ V}$ ,  $T_a = 25^\circ\text{C}$ )

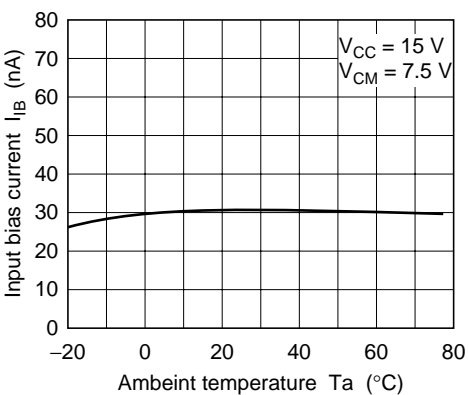
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input offset voltage	$V_{IO}$	—	2	7	mV	$V_{CM} = 7.5\text{ V}$ , $R_S = 50\ \Omega$ , $R_f = 50\text{ k}\Omega$
Input offset current	$I_{IO}$	—	5	50	nA	$V_{CM} = 7.5\text{ V}$ , $I_{IO} =  I_{I(-)} - I_{I(+)} $
Input bias current	$I_{IB}$	—	30	500	nA	$V_{CM} = 7.5\text{ V}$
Power source rejection ratio	PSRR	—	93	—	dB	$f = 100\text{ Hz}$ , $R_S = 1\text{ k}\Omega$ , $R_j = 100\text{ k}\Omega$
Voltage gain	$A_{VD}$	75	90	—	dB	$R_S = 1\text{ k}\Omega$ , $R_f = 100\text{ k}\Omega$ , $R_L = \infty$
Common mode rejection ratio	CMR	—	80	—	dB	$R_S = 50\ \Omega$ , $R_f = 5\text{ k}\Omega$
Common mode input voltage range	$V_{CM}$	-0.3	—	13.5	V	$R_S = 1\text{ k}\Omega$ , $R_f = 100\text{ k}\Omega$ , $f = 100\text{ Hz}$
Maximum output voltage	$V_{op-p}$	—	13.6	—	V	$f = 100\text{ Hz}$ , $R_S = 1\text{ k}\Omega$ , $R_f = 100\text{ k}\Omega$ , $R_L = 20\text{ k}\Omega$
Output source current	$I_{osource}$	20	40	—	mA	$V_{IN}^+ = 1\text{ V}$ , $V_{IN}^- = 0\text{ V}$ , $V_{OH} = 10\text{ V}$
Output sink current	$I_{osink}$	10	20	—	mA	$V_{IN} = 0\text{ V}$ , $V_{IN} = 1\text{ V}$ , $V_{OL} = 2.5\text{ V}$
Supply current	$I_{CC}$	—	0.8	2	mA	$V_{IN} = \text{GND}$ , $R_L = \infty$
Slew rate	SR	—	0.19	—	V/ $\mu\text{s}$	$f = 1.5\text{ kHz}$ , $V_{CM} = 7.5\text{ V}$ , $R_L = \infty$
Channel separation	CS	—	120	—	dB	$f = 1\text{ kHz}$
Output sink current	$I_{osink}$	15	50	—	$\mu\text{A}$	$V_{IN}^+ = 0\text{ V}$ , $V_{IN}^- = 1\text{ V}$ , $V_{OL} = 200\text{ mV}$
	$I_{osink}$	3	9	—	mA	$V_{IN}^+ = 0\text{ V}$ , $V_{IN}^- = 1\text{ V}$ , $V_{OL} = 1\text{ V}$
Output voltage	$V_{OH}$	13.2	13.6	—	V	$I_{OH} = -1\text{ mA}$
	$V_{OH}$	12.0	13.3	—	V	$I_{OH} = -10\text{ mA}$
Output voltage	$V_{OL}$	—	0.8	1.0	V	$I_{OL} = 1\text{ mA}$
	$V_{OL}$	—	1.1	1.8	V	$I_{OL} = 10\text{ mA}$

Characteristic Curves

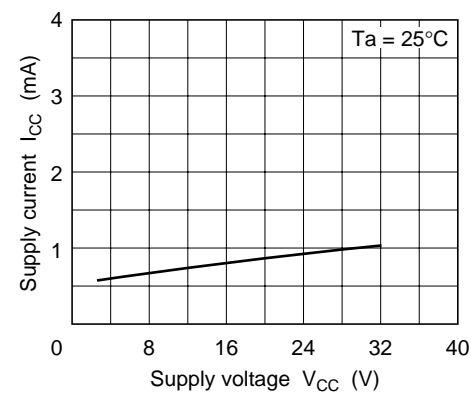
Output Source Current vs. Ambient Temperature



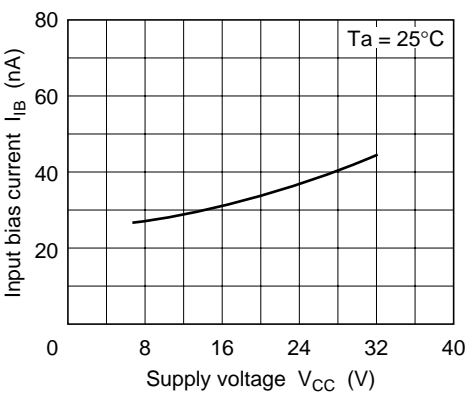
Input Bias Current vs. Ambient Temperature



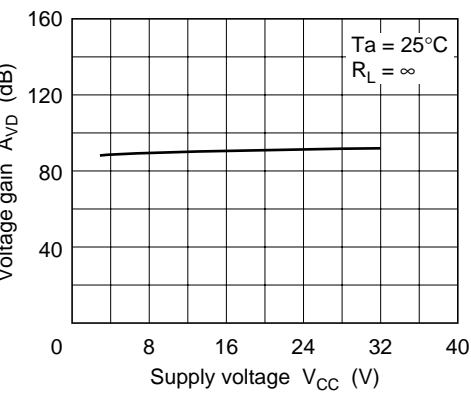
Supply Current vs. Supply Voltage



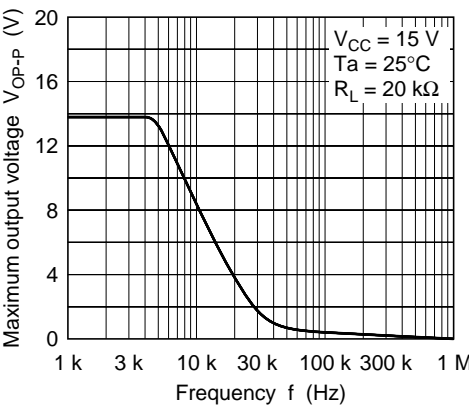
Input Bias Current vs. Supply Voltage

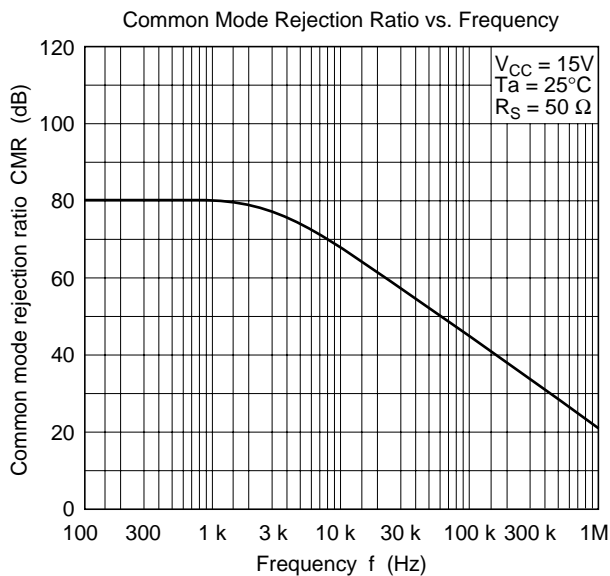
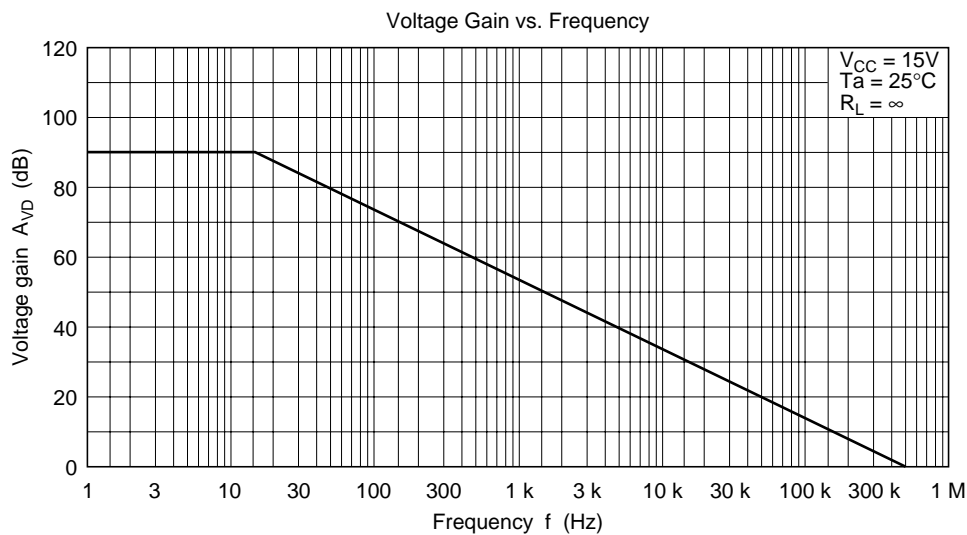


Voltage Gain vs. Supply Voltage



Maximum Output Voltage vs. Frequency





Solder Mounting Method

- 1. Small and light surface-mount packages require spicial attentions on solder mounting.  
On solder mounting, pre-heating before soldering is needed.  
The following figure show an example of infrared rays reflow.
- 2. The difference of thermal expansion coefficeient between mounted substrates and IC leads may cause a failure like solder peeling or soler wet, and electrical characteristics may change by thermal stress.  
Therefore, mounting should be done after sufficient confirmation for especially in case of ceramic substrates.

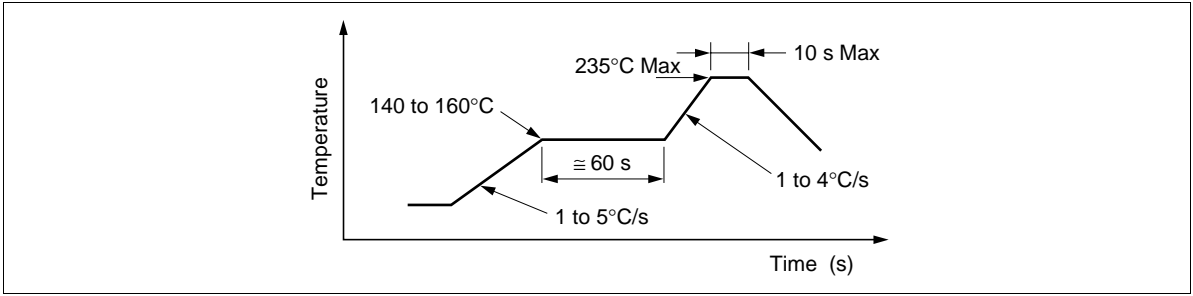
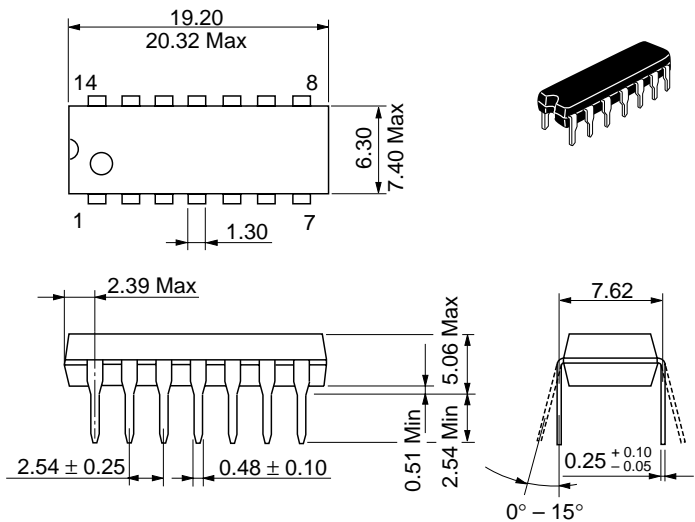


Figure 1 An Example of Infrared Rays Reflow Conditions



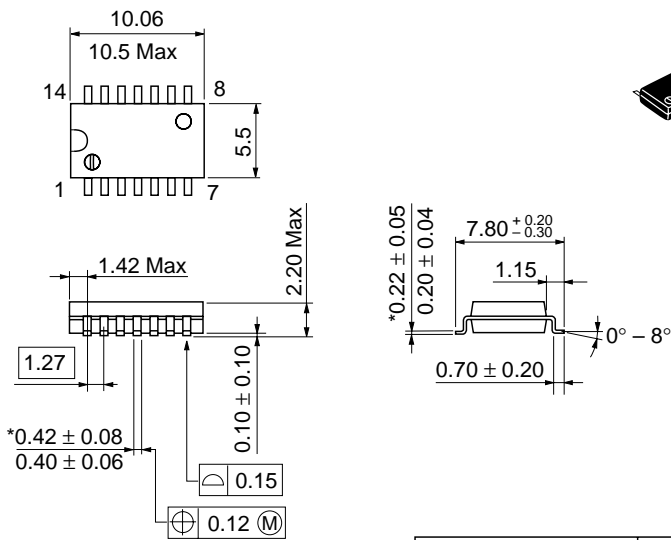
Package Dimensions

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.97 g

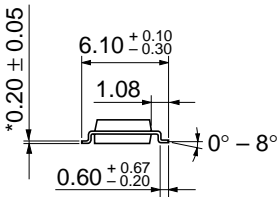
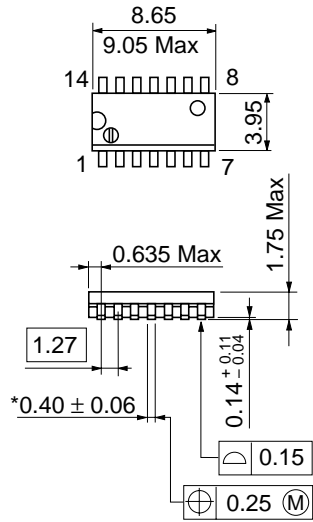
Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.23 g

Unit: mm



\*Pd plating

Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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## Hitachi, Ltd.

Semiconductor & Integrated Circuits.  
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan  
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica	: <a href="http://semiconductor.hitachi.com/">http://semiconductor.hitachi.com/</a>
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## For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1> (408) 433-0223	Hitachi Europe GmbH Electronic components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00  Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322
--	---

Hitachi Asia Pte. Ltd.  
16 Collyer Quay #20-00  
Hitachi Tower  
Singapore 049318  
Tel: 535-2100  
Fax: 535-1533

Hitachi Asia Ltd.  
Taipei Branch Office  
3F, Hung Kuo Building, No.167,  
Tun-Hwa North Road, Taipei (105)  
Tel: <886> (2) 2718-3666  
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.  
Group III (Electronic Components)  
7/F., North Tower, World Finance Centre,  
Harbour City, Canton Road, Tsim Sha Tsui,  
Kowloon, Hong Kong  
Tel: <852> (2) 735 9218  
Fax: <852> (2) 730 0281  
Telex: 40815 HITEC HX

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